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Dear Analysts

I am pleased to share Sasken Group's performance for the quarter ended September 30, 2026. Certain statements in this note, and in our remarks concerning future growth, may constitute forward-looking statements. Please refer to the Safe Harbour statement at the end of this document.

Sasken closed the quarter with revenues of ₹321 crore, a growth of 26% year on year. Profit after tax was ₹26 crore with a meaningful margin expansion by 387 basis points over last year. This reflects our continuing focus on scale, strategic investments, and disciplined execution.

Software Services grew 15% sequentially and 34% year-on-year, supported by deeper participation in strategic customer programmes, improved scale and increasing engineering ownership.

Product Solutions moderated 42% sequentially but increased by 2.4% year-on-year, primarily due to lower shipment volumes arising from continued component-supply tightness as we communicated in our previous discussions. Despite this, consolidated revenue remained 26% higher year-on-year, underscoring the stronger base we have built over recent quarters.

It is also important to view our two businesses in the context of their different operating models. Software Services lends itself to quarterly assessment, while Product Solutions is influenced by programme timing, shipment cycles and product life cycles. We therefore believe its performance is better assessed over a longer horizon rather than through any single quarter.

On profitability, EBIT increased 31% sequentially, with margins expanding by approximately 248 basis points. This was driven by better utilisation, operating efficiencies and disciplined cost management, even as we implemented annual salary revisions across levels in July in keeping with Sasken's established commitment to its people.The quarter echoes the progress we are making in scaling the business with greater discipline, while continuing to invest in the talent and capabilities required to support long-term growth.

Beyond the quarter's numbers, we continued to deepen customer relationships and expand our participation across automotive, semiconductors, communications, connected devices, and digital engineering. Across several accounts, our role is progressing from capacity-led support towards longer-duration, solution-oriented and platform-led engagements.

As we move into H2 FY27, our priorities remain to sustain Services momentum, manage Product Solutions through the current supply environment, and convert recent wins into revenue. We remain disciplined in execution and confident in the direction of the business.

Key Financial Highlights

- Consolidated PAT for Q2 FY27 was at ₹ 25.59 crores, up 8.8% over the previous quarter. PAT margin for Q2 FY27 was at 8%.

Performance Snapshot for the Quarter: Q2 FY27

- Consolidated Revenues for Q2 FY27 at ₹ 320.95 crores
  - Down 5.4% sequentially over the previous quarter
  - Up 25.6% YoY from Q2 FY26
- Consolidated EBIT for Q2 FY27 at ₹ 28.49 crore
  - Up 31.2% sequentially over the previous quarter
  - Up 394.3% YoY from Q2 FY26
  - EBIT margin for the quarter was 8.9%.
- Consolidated PAT for Q2 FY27 at ₹ 25.59 crore
  - Up 8.8% sequentially over the previous quarter
  - Up 143.8% YoY from Q2 FY26
  - PAT margin for the quarter at 8.0%

Key business metrics

- Revenue contribution from the Top 5 customers stood at 49% and from the Top 10 customers at 63%.
- Consolidated EPS was at ₹ 16.14 for Q2 FY27.
- Cash & Cash equivalents were ₹398.8 crores at the end of the quarter.

New Deals and Order Book

Total contract value booked during the quarter stood at $**47.3** million, out of which **$24.8** million came from new business. We also added four new logos.

Below are the key order wins:

- Secured a multi-year, multi-million-dollar mega engineering engagement with a leading European automotive group to support next-generation telematics development, integration, validation and commercialisation.
- Won an innovative asset-tracking solution deal to integrate smart tracker devices, web platform and mobile application to manage fibre reels and associated assets.
- Won a strategic engineering engagement with a leading European automotive OEM to own and deliver critical Cockpit and ADAS programs from India.
- Won a multi-skilled engineering engagement with a leading Indian EV company across application development, HMI, middleware and testing for advanced electric mobility platforms.
- Won an end-to-end semiconductor IP engagement for a cellular SoC, covering RF, power management, audio and analog IP design through tapeout, silicon validation and production support with a leading semiconductor company.

Our People

During Q2 FY27, our people agenda remained closely aligned with Sasken's growth priorities and Chip-to-Cognition strategy. We continued to focus on workforce growth, retention, capability

building, recognition and scalable people processes. Headcount increased by approximately 7% to 2,844, while trailing 12-month attrition stood at 9.3% and annualised attrition at 8.0%, reflecting continued workforce stability.

Closer collaboration between HR and Delivery teams enabled more proactive engagement with employees, high-potential talent and project teams, supporting focused retention and faster response to business needs. We also continued to invest in employee well-being through professional counselling and the pilot introduction of the Mio well-being platform.

Recognition and career development remained important priorities during the quarter. More than 225 employees were recognised across performance, learning and functional excellence categories. Recognition programmes were also extended across subsidiaries, while promotions and internal mobility supported career progression and diverse leadership pipelines.

Capability building continued through leadership development, targeted learning and structured GenAI programmes designed to strengthen business-aligned and future-ready skills. Technology-enabled HR transformation also progressed with KenGenie, our AI-powered policy assistant, and the enhanced Hirewand talent-acquisition platform.

We inaugurated a new ODC for a core programme that has scaled to 200 employees, reflecting continued business growth and investment in collaborative work environments. Our people and organisational practices also received external recognition across CMMI maturity, workforce management, ESG, women's inclusion, CSR and environmental sustainability.

As we move ahead, our focus remains on sustaining workforce stability, strengthening specialist and leadership capabilities, and scaling technology-enabled people processes to support Sasken's next phase of growth.

Business Highlights

The engineering R&D market is changing in a fundamental way. AI, software-defined architectures, and intelligent connectivity are no longer separate technology themes; they are increasingly coming together within the product itself. As this happens, customers are looking beyond individual engineering skills and seeking partners who can take greater responsibility across silicon, software, devices, and intelligence.

This shift continues to align well with Sasken's Chip-to-Cognition strategy. Our objective is not simply to participate in more areas of the engineering value chain, but to connect these capabilities in ways that allow us to solve larger customer problems, take greater product ownership and build relationships that endure over multiple technology and product cycles.

We saw encouraging evidence of this during Q2. In automotive, we secured a $15 million, four-and-a-half-year telematics programme with a European OEM and expanded our relationship with a German Tier-1 through new programmes. We are complementing such engagements with investments in our own platforms, IP and automotive toolchains, and with joint go-to-market initiatives alongside chipset companies and ISVs. In parallel, we continue to build opportunities across semiconductor engineering, advanced communications, connected devices, and AI-led digital engineering.

What is important to us is how the business is evolving. Over time, we would like to see a greater contribution from longer-duration programmes, reusable engineering assets and platform-led

solutions, while continuing to support customers where capacity-led engagement remains relevant.

As we move through FY27, we will continue to build these capabilities with discipline. Our ambition is to make Sasken increasingly relevant to our customers' product roadmaps while creating a more diversified, resilient, and higher-value engineering business for the long term.

Automotive

The automotive industry continues to move towards software-defined, connected and increasingly intelligent vehicle architecture. For Sasken, this is creating opportunities to participate more deeply across telematics, digital cockpit, and software-defined vehicle platforms, while moving progressively from engineering services towards solution-led and IP-backed engagements.

We are also investing in reusable platforms and IP to improve development efficiency for customers. Our in-house KenAPT and KenQual platforms are helping us build chipset-agnostic software solutions across digital cockpit and telematics, reducing development time, validation effort, and overall programme cost. Alongside this, we are working with leading chipset providers and ISVs through joint go-to-market initiatives to bring more integrated solutions to global OEMs.

Looking ahead, our focus remains on strengthening Sasken's role as an automotive integrator and gradually increasing the contribution of IP-led solutions. We are investing in GenAI-enabled engineering, automotive tool chains and emerging areas such as service-oriented architectures, while continuing to build depth across telematics, digital cockpit and SDV platforms running on high-performance compute architectures.

Networks, SatCom and Mission-Critical Communications

Terrestrial and non-terrestrial networks are increasingly converging across consumer, automotive, IoT and mission-critical applications. At the same time, Private 5G, hybrid networks and specialised communication systems are gaining relevance across public safety, transportation, industrial and critical-infrastructure environments.

For Sasken, these shifts build on our long-standing communications expertise and expand the opportunity across TN-NTN integration, mission-critical communications and specialised devices. Our work with chipset, device and network ecosystems allows us to participate across both software and device engineering.

Building on our multi-year product-development engagement with a European provider of mission-critical communication solutions for Europe and the Middle East, we continue to sharpen our focus on PPDR, Critical Communications and Private 5G. In India, the emphasis on Atmanirbhar Bharat and Design and Make in India is creating opportunities for rugged handhelds, dispatch consoles and purpose-built products for airports, railways, seaports and other critical infrastructure.

Our ODM capabilities further strengthen our ability to support OEMs, system integrators and operators as a design and supply-chain partner. We are seeing encouraging customer interest and remain focused on building differentiated solutions around our core engineering strengths.

As early 6G activity progresses and TN-NTN coexistence becomes more important, we also see opportunities in validation, interoperability and platform readiness. Our focus will remain on converting these shifts into repeatable programmes and deeper customer relationships across India and global markets.

Smart Devices

The smart devices market continues to evolve around on-device AI, 5G, satellite-enabled connectivity and growing demand for purpose-built enterprise devices. We are also seeing an important transition in mission-critical communications, where traditional technologies such as LMR, DMR and P25 are increasingly being complemented by 3GPP-based and hybrid architectures. Over time, technologies such as NR Sidelink are expected to further expand device-to-device and mission-critical connectivity use cases.

In India, demand is also increasing for ruggedised and specialised devices that are designed and manufactured locally. Requirements around security, reliability, localisation and lifecycle support are becoming more important across enterprise, industrial and public-sector applications. This creates a relevant opportunity for Sasken given our combination of device engineering, embedded software, semiconductor capabilities and ODM ecosystem.

During Q2, we made tangible progress across both ODM and device software services. We expanded our focus on higher-value enterprise and specialised device programmes, progressed new customer discussions across multiple categories and continued to broaden the programme mix. During the quarter, we also launched Juniper Alta, a new device developed end-to-end and brought to shipment within 18 months. The programme demonstrates our ability to take products from concept through engineering and commercialisation. This execution has also led to an expanded mandate covering turnkey development and lifecycle management of a key product from a large hyperscaler

Within device software services, we progressed from capacity-led support towards broader product responsibility across multiple chipset platforms. Our role is expanding across development, validation and lifecycle support, reflecting deeper engineering ownership and longer-duration customer relationships.

In India, we continued to build opportunities across point-of-sale devices, automotive Network Access Device modules, NTN-enabled products, rugged devices and computer-vision camera platforms. These areas align well with demand for intelligent, connected and locally engineered products.

Looking ahead, our focus will be on increasing platform and software reuse, deepening product ownership and improving the mix of enterprise and specialised devices. The combination of Sasken's engineering capabilities and Borqs' ODM experience enables us to support customers from product architecture and embedded development through certification, manufacturing coordination and post-market support.

The progress made in Q2 gives us greater confidence in the direction of the business. We remain measured in how we scale, with a clear focus on building a more resilient, diversified and higher-value Smart Devices portfolio

Data Science & Engineering

Enterprise AI is moving from experimentation towards scaled deployment. Agentic AI is increasingly being applied to business workflows and technology operations, while customers are placing greater emphasis on the reliability, governance and cost of AI systems as they move into production. Data platforms are also evolving towards AI-native architectures, increasing the importance of high-quality data, modern data pipelines and stronger governance frameworks.

These shifts are creating opportunities across both AI-led engineering and data modernisation. During the quarter, we continued to strengthen our Data Science & Engineering portfolio around industry-specific GenAI solutions, multi-agent automation, data engineering and AI governance.

A key area of progress has been our Multi-Agentic AI SRE offering, designed to improve the performance, resilience and operational efficiency of complex digital platforms through proactive monitoring and intelligent automation. This offering has created engagement opportunities multiple customers.

We also expanded industry-focused AI solutions across automotive, manufacturing, communications and smart devices, helping deepen existing relationships and open new customer conversations. Our emphasis remains on applying AI to specific engineering and business problems rather than treating it as a standalone technology.

Data engineering is becoming increasingly important as customers move from traditional analytics towards GenAI and agentic applications. We are investing in data platforms, pipelines, unified data management and governance to provide the foundations required for AI-native workloads.

We are also developing reusable solutions such as Tokenomics to help customers manage the rising cost of AI token consumption and improve the economics of GenAI deployments. Together, these capabilities strengthen the cognition layer of our Chip-to-Cognition strategy and broaden our ability to support customers across AI-led transformation programmes.

Semiconductor

AI infrastructure is broadening semiconductor demand beyond compute into memory, networking, power management, analog and optical interconnects, while custom silicon and AI-assisted chip design are gaining importance. At the same time, customers are looking for greater customisation and faster design cycles, increasing the relevance of reusable IP and AI-assisted engineering.

These trends align well with Sasken Silicon's position as a specialised semiconductor engineering and IP partner, rather than a chip manufacturer**.** We work with semiconductor companies and system customers across IP development, analog and mixed-signal design, connectivity, physical design, verification, and system-level engineering, helping accelerate the path from architecture to production-ready silicon.

During the quarter, we continued execution across RF, power-management, and connectivity IP, including silicon-validated Wi-Fi and sub-GHz technologies, while expanding IP licensing engagements. We are also strengthening capabilities for AI infrastructure through specialised

memory, high-speed interface, and optical-interconnect IP, while applying AI within our own design flows to improve productivity and shorten development cycles.

Connectivity remains another area of opportunity as terrestrial and satellite architectures converge. We are extending our RF and modem roadmap to address these emerging requirements.

Our focus remains on building deeper specialist capabilities, increasing reusable IP and converting this engineering depth into design wins, licensing opportunities, and longer-duration customer programmes.

My team and I sincerely appreciate the confidence you have shown in us, and we remain fully committed to acting in the best interests of all our stakeholders and delivering on the responsibilities entrusted to us.

Sincerely,

Rajiv C. Mody

Chairperson, Managing Director & CEO

Disclaimer on Forward Looking Statements:

Certain statements in this release concerning our future growth prospects are forward-looking statements, which involve a number of risks, and uncertainties that could cause actual results to differ materially from those in such forward-looking statements due to risks or uncertainties associated with our expectations with respect to, but not limited to, our ability to successfully implement our strategy and our growth and expansion plans, technological changes, our exposure to market risks, general economic and political conditions which have an impact on our business activities or investments, changes in the laws and regulations that apply to the services industry, including with respect to tax incentives and export benefits, adverse changes in foreign laws, including those relating to outsourcing and immigration, increasing competition in and the conditions of the Indian and global IT services industry, the prices we are able to obtain for our services, wage levels for IT professionals, the loss of significant customers, the monetary policies in India and globally, inflation, deflation, unanticipated turbulence in interest rates, foreign exchange rates, equity prices or other rates or prices, the performance of the financial markets in India and globally. The Company may, from time to time, make additional written and oral forward-looking statements, including statements contained in the Company's filings with the Stock Exchanges and our reports to shareholders. The Company does not undertake to update any forward-looking statement that may be made from time to time by or on behalf of the Company.